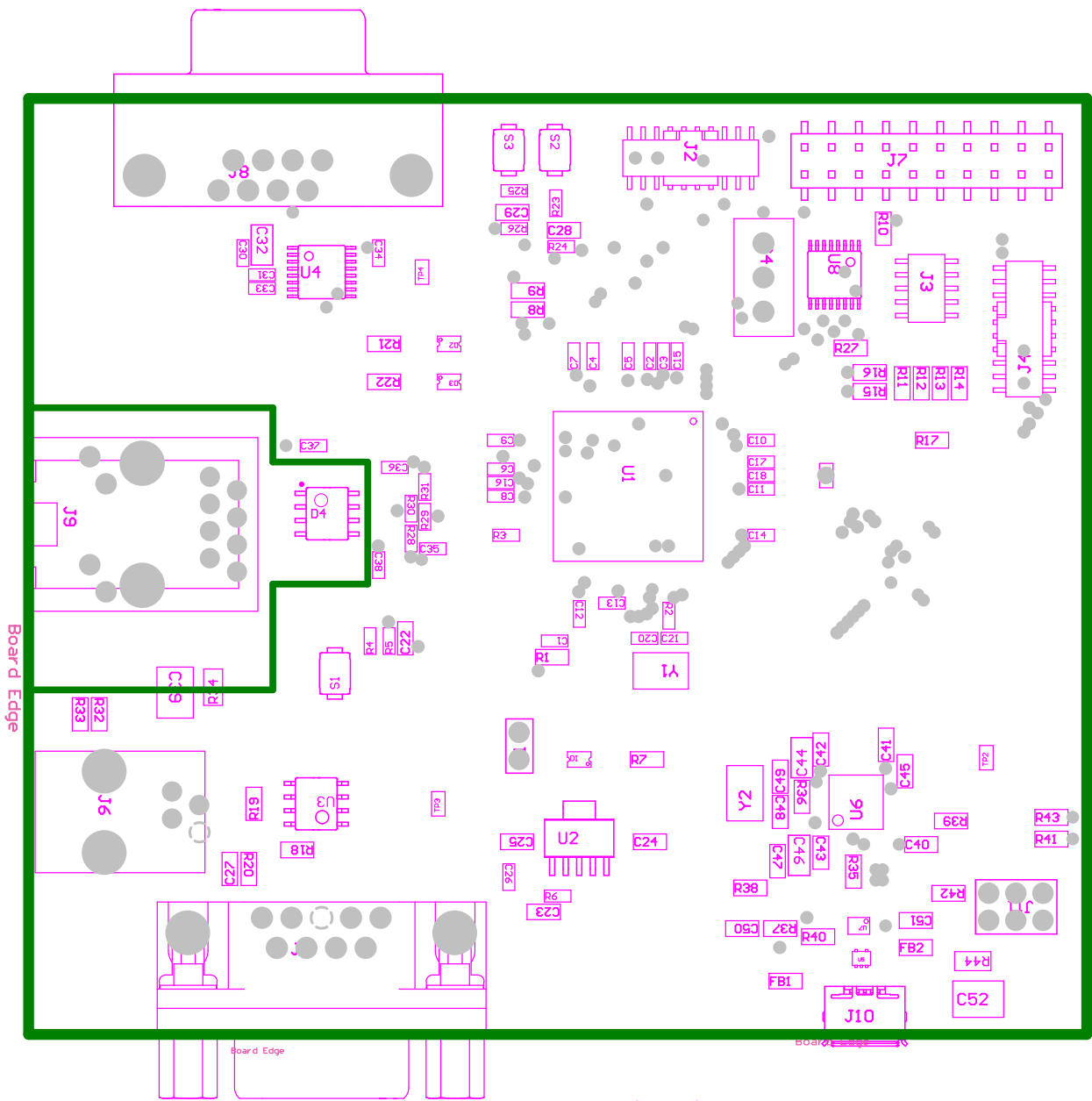


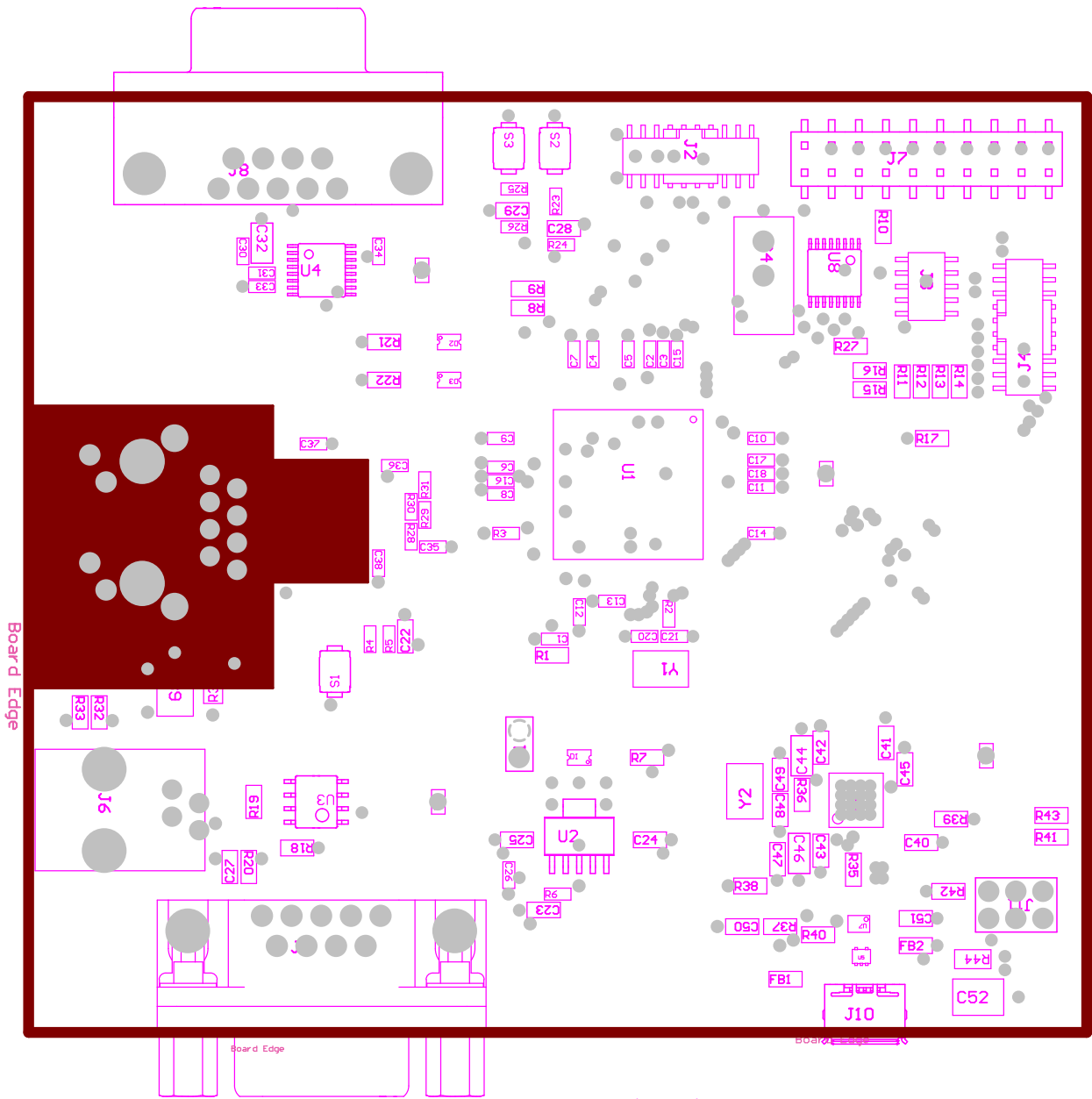
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDM-TM4C129USBHS	REV: A0	SUN REV: Not In VersionControl
LAYER NAME = Component Side	TID #: TIDM-TM4C129USBHS		
PLOT NAME = Component Side	GENERATED : 9/9/2016	3:24:27 PM	TEXAS INSTRUMENTS



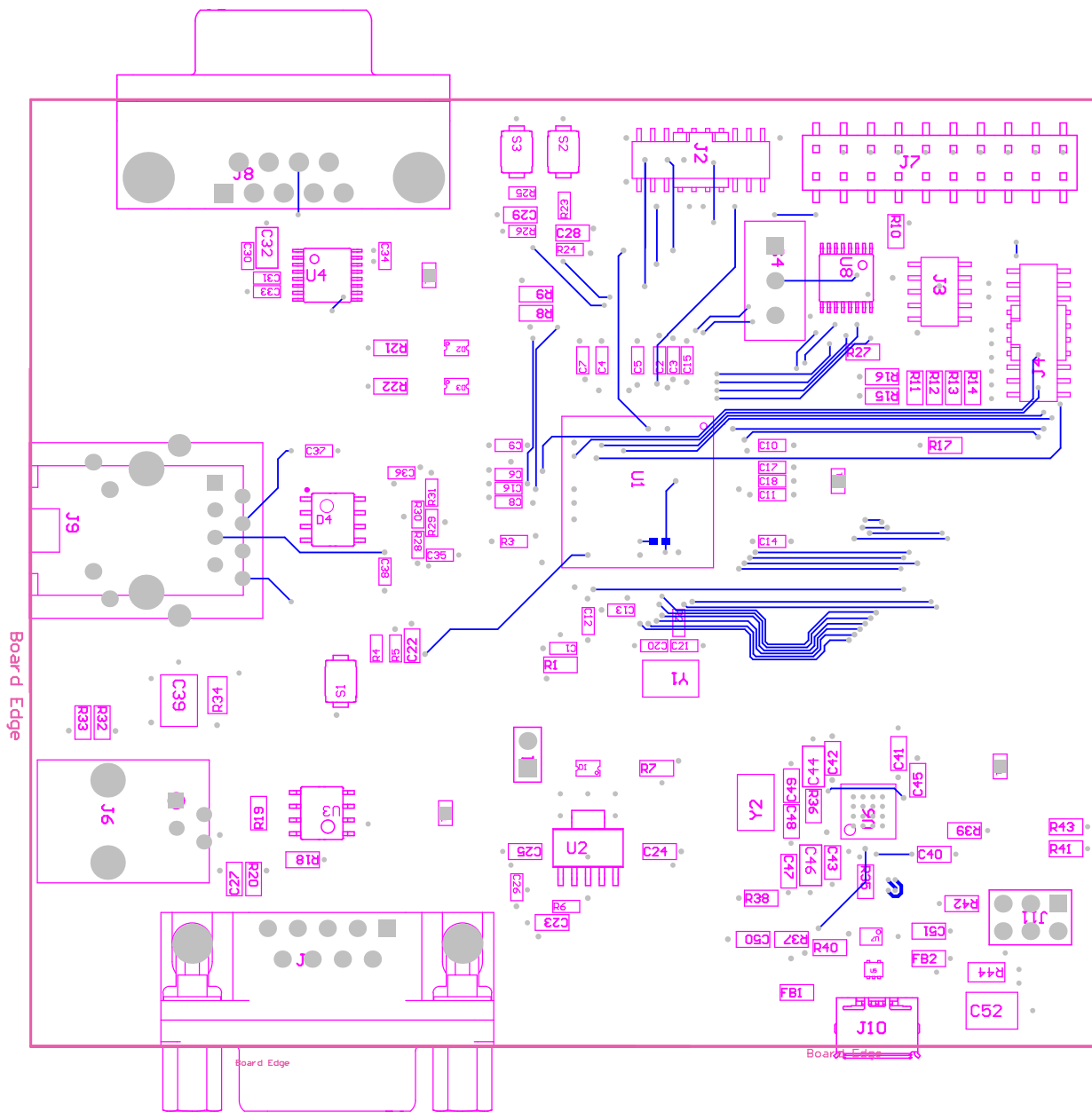
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDM-TM4C129USBHS	REV: A0	SUN REV: Not In VersionControl
LAYER NAME = Ground Plane	TID #: TIDM-TM4C129USBHS		
PLOT NAME = Ground Plane <<Multiple Nets>>	GENERATED : 9/9/2016	3:24:27 PM	TEXAS INSTRUMENTS



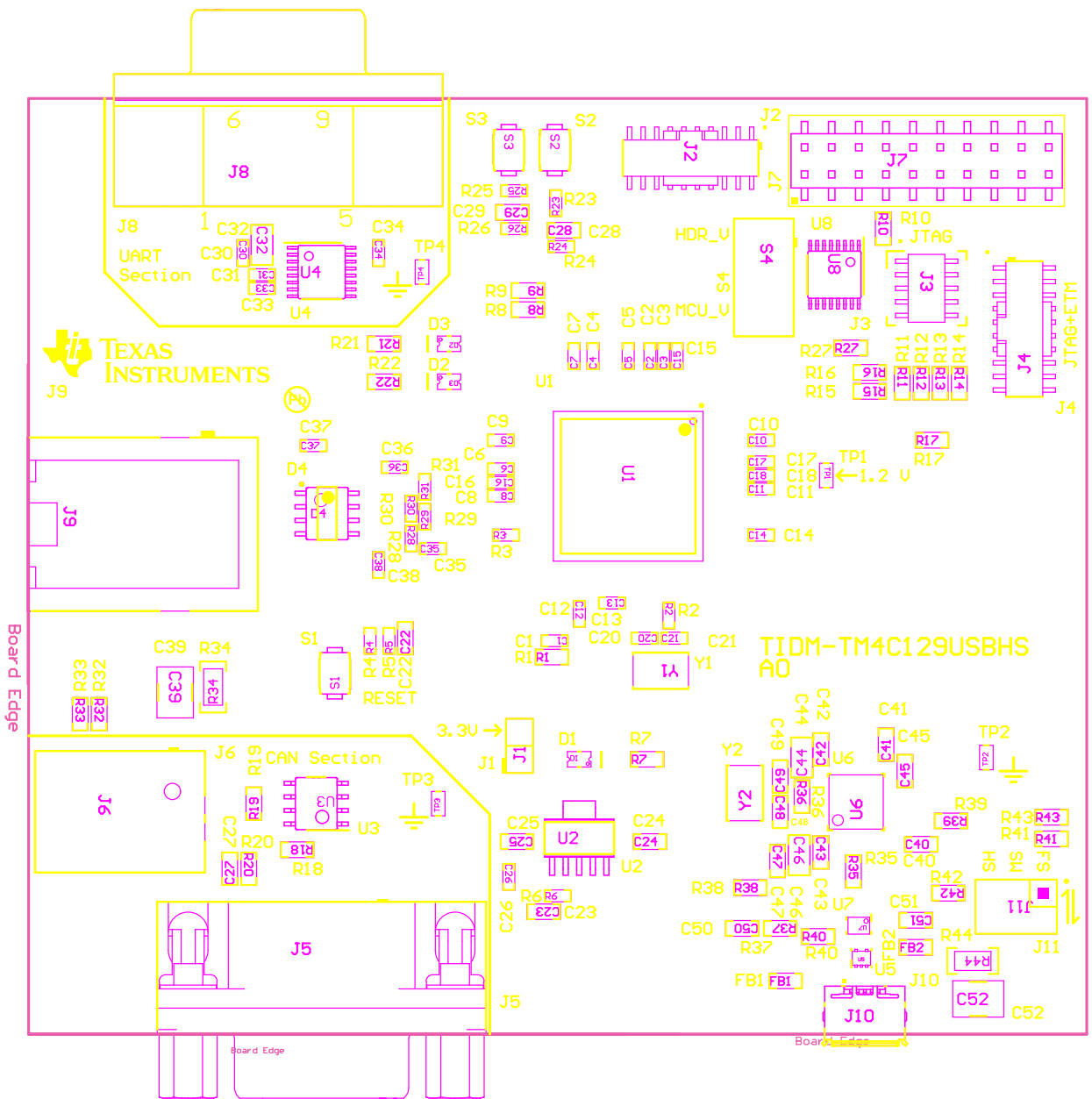
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDM-TM4C129USBHS	REV: A0	SUN REV: Not In Version Control
LAYER NAME = Power Plane	TID #: TIDM-TM4C129USBHS		
PLOT NAME = Power Plane (UCC_3P3)	GENERATED : 9/9/2016	3:24:28 PM	TEXAS INSTRUMENTS



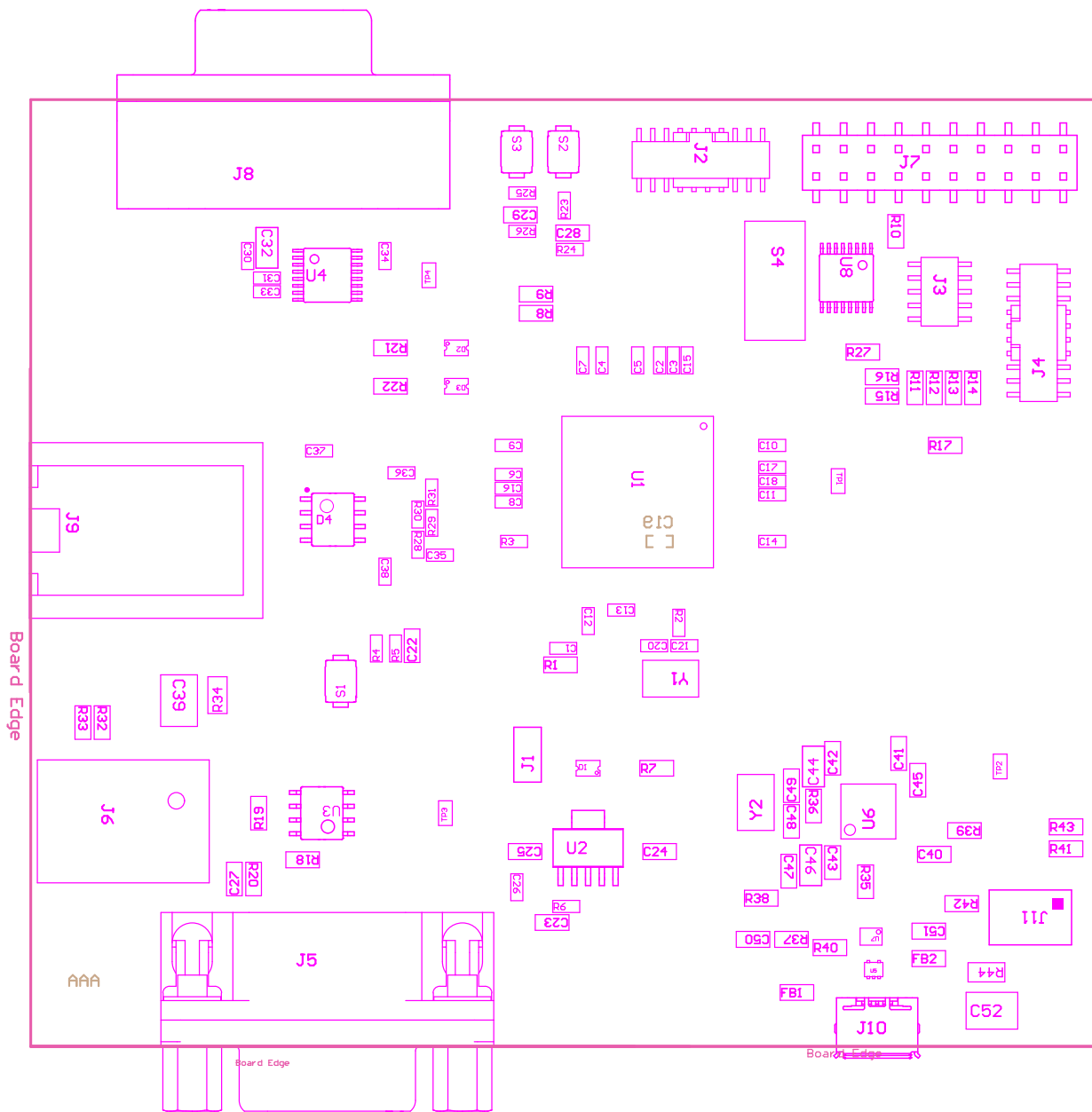
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDM-TM4C129USBHS	REV: A0	SUN REV: Not In VersionControl
LAYER NAME = Solder Side	TID #: TIDM-TM4C129USBHS		
PLOT NAME = Solder Side	GENERATED : 9/9/2016	3:24:29 PM	TEXAS INSTRUMENTS



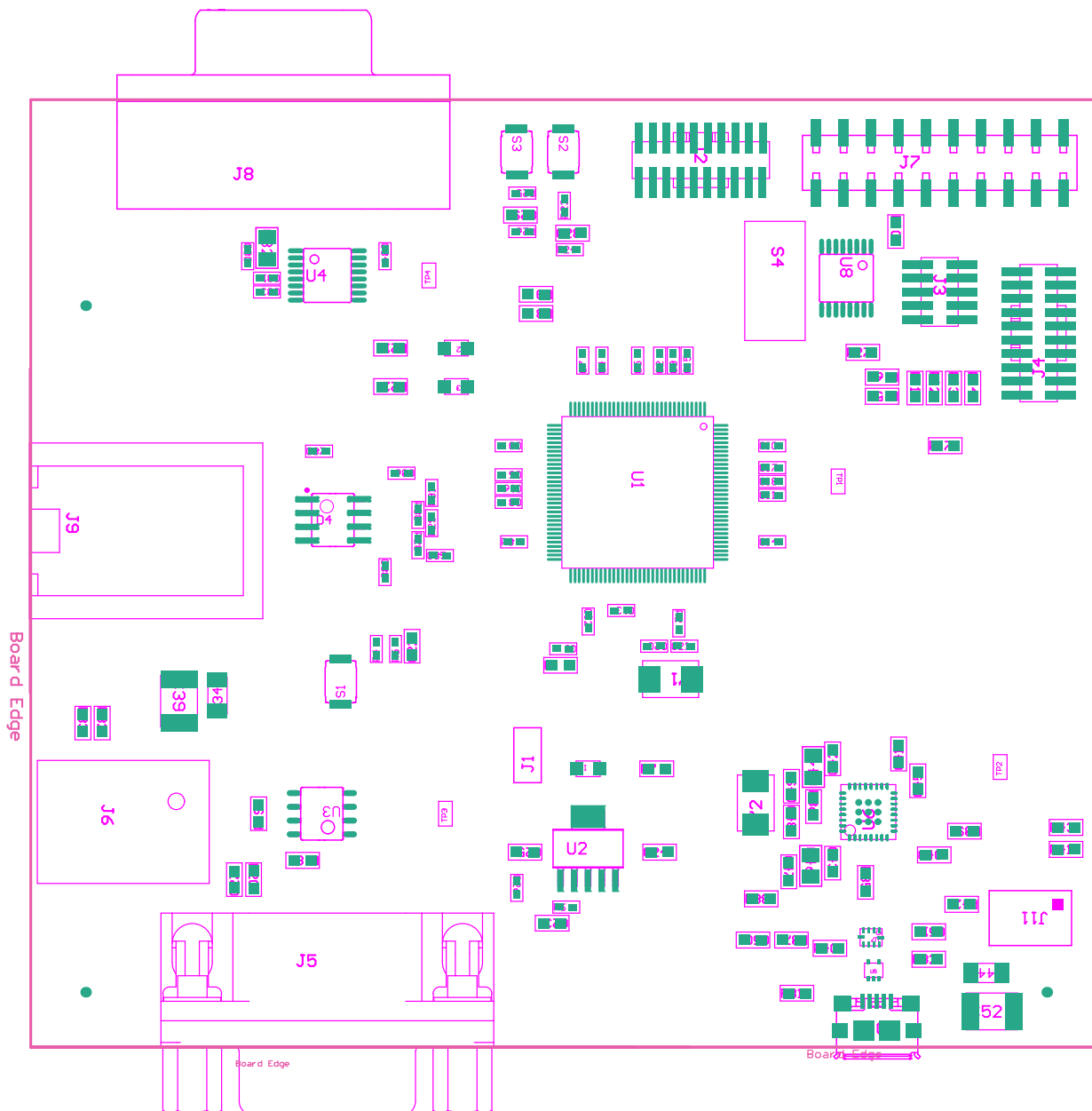
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDM-TM4C129USBHS	REV: A0	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDM-TM4C129USBHS		
PLOT NAME = Top Silkscreen Overlay	GENERATED : 9/9/2016	3:24:29 PM	TEXAS INSTRUMENTS



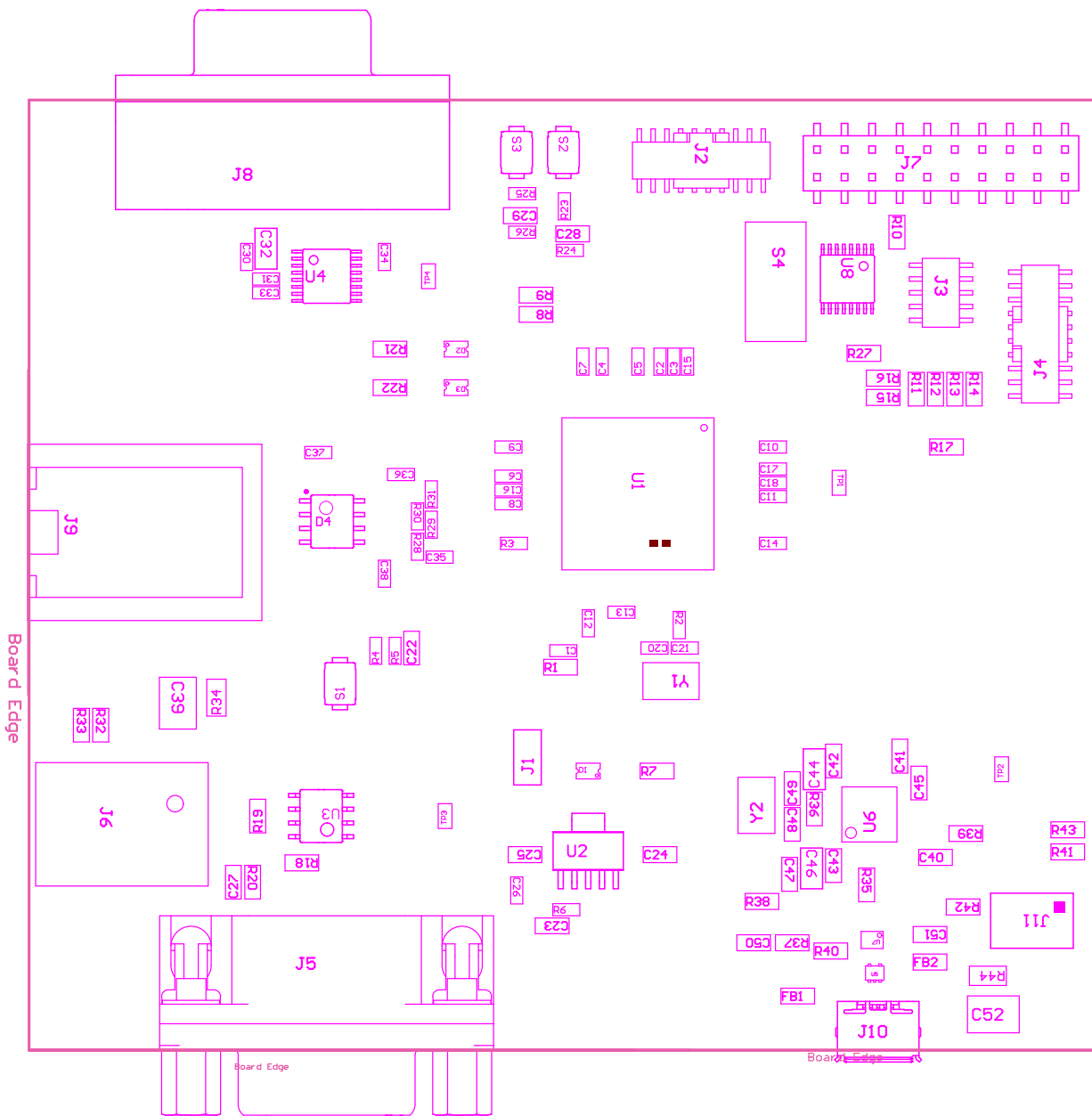
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDM-TM4C129USBHS	REV: A0	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDM-TM4C129USBHS		
PLOT NAME = Bottom Silkscreen Overlay	GENERATED : 9/9/2016	3:24:30 PM	TEXAS INSTRUMENTS



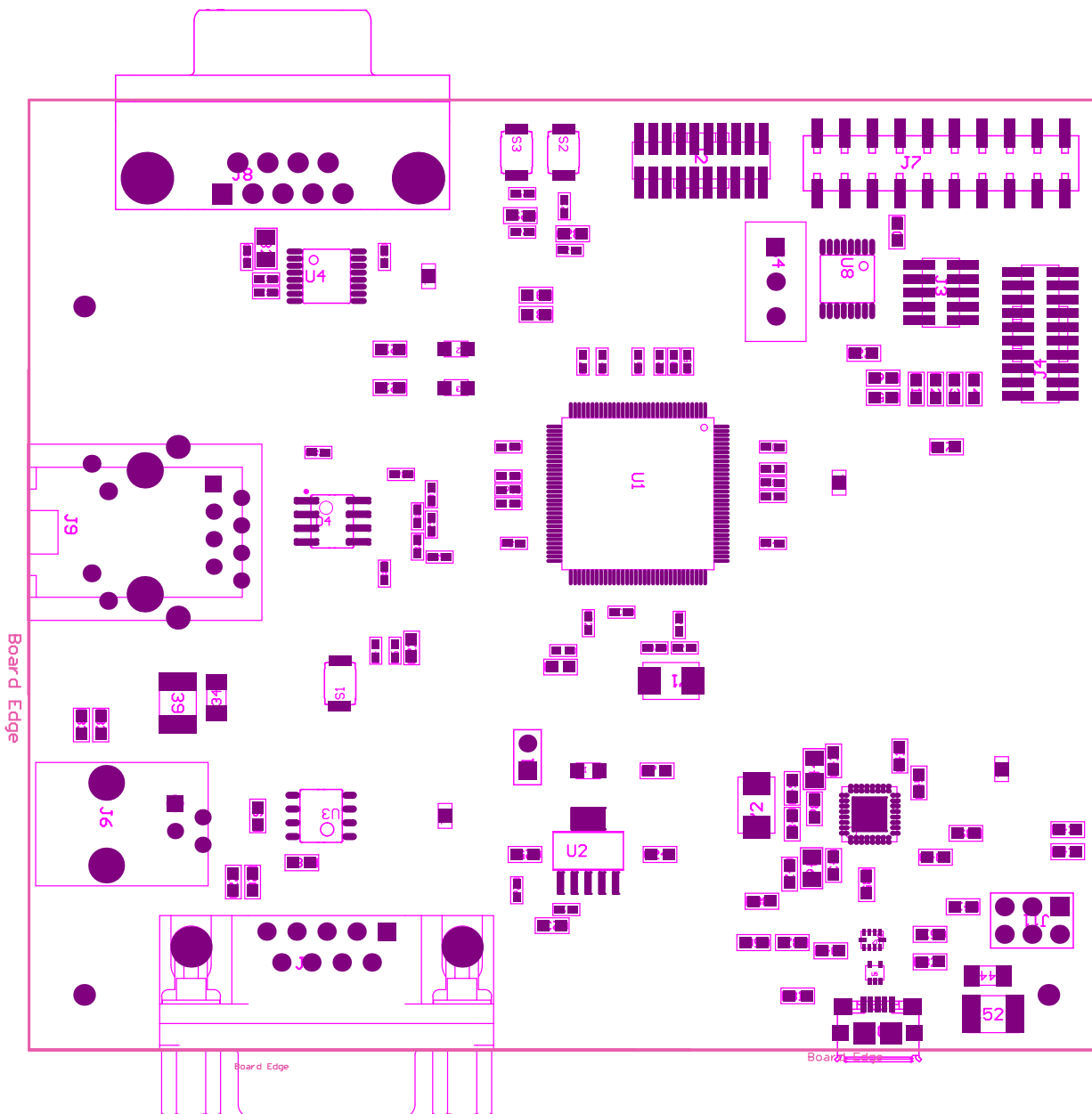
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDM-TM4C129USBHS	REV: A0	SUN REV: Not In VersionControl
LAYER NAME = Top Paste	TID #: TIDM-TM4C129USBHS		
PLOT NAME = Top Paste Mask Print	GENERATED : 9/9/2016	3:24:31 PM	TEXAS INSTRUMENTS



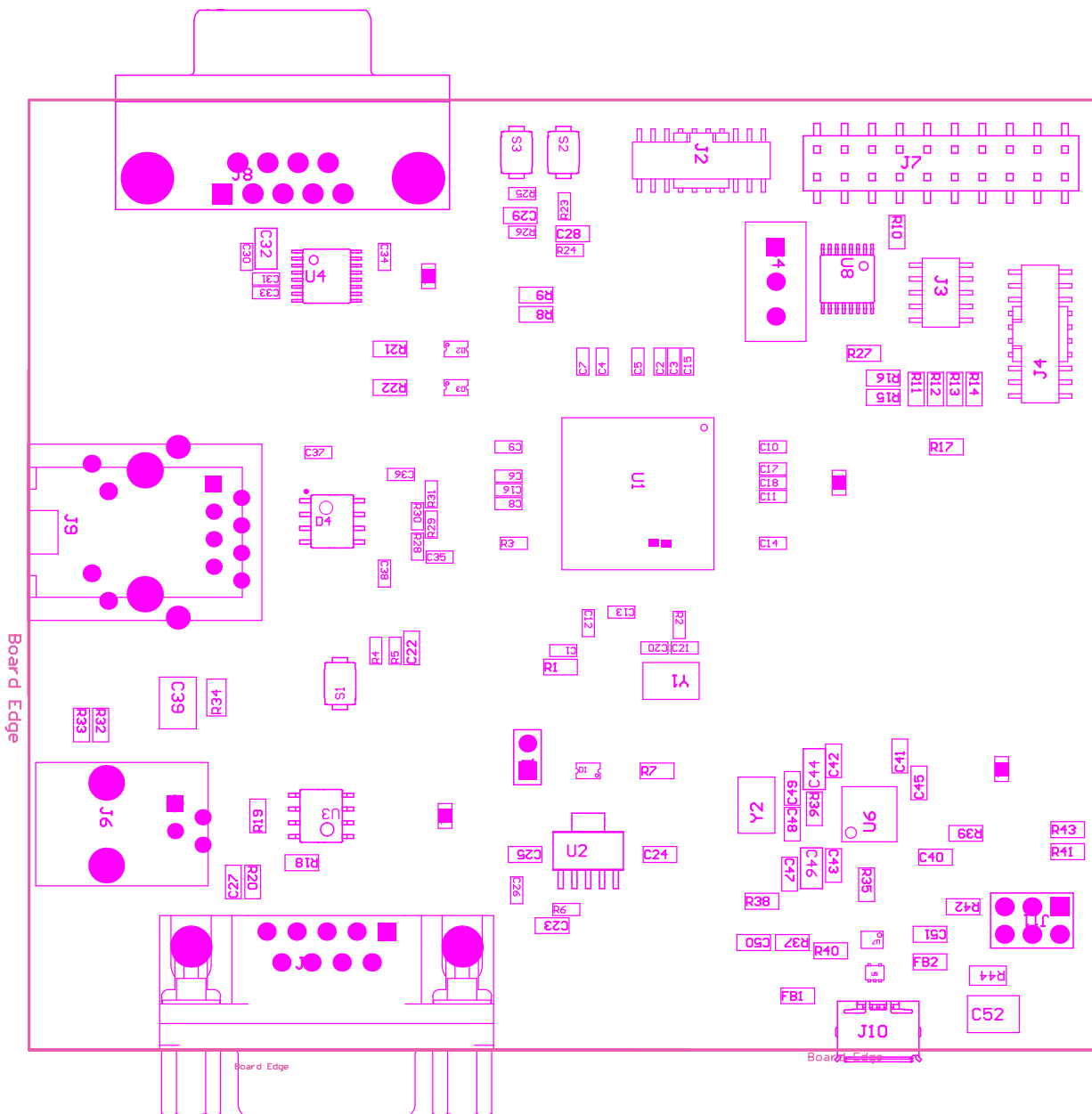
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDM-TM4C129USBHS	REV: A0	SUN REV: Not In VersionControl
LAYER NAME = Bottom Paste	TID #: TIDM-TM4C129USBHS		
PLOT NAME = Bottom Paste Mask Print	GENERATED : 9/9/2016	3:24:32 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDM-TM4C129USBHS	REV: A0	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDM-TM4C129USBHS		
PLOT NAME = Top Solder Mask Print	GENERATED : 9/9/2016	3:24:32 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDM-TM4C129USBHS	PHS: A0	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDM-TM4C129USBHS		
PLOT NAME = Bottom Solder Mask Print	GENERATED : 9/9/2016	3:24:33 PM	TEXAS INSTRUMENTS

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